



033792R003

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Lei LU, et al.

U.S. Serial No.: 10/532,674

Group Art Unit: To Be Assigned

Filed: : April 26, 2005

Examiner: To Be Assigned

For: NANO-TWIN COPPER MATERIAL WITH ULTRAHIGH STRENGTH AND
HIGH CONDUCTIVITY AND ITS PREPARATION METHODSECOND INFORMATION DISCLOSURE STATEMENTCommissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure under 37 C.F.R. 1.56, Applicants are enclosing an Information Disclosure Citation Form (PTO-1449) and copies of the non-U.S. documents cited therein.

It is respectfully requested that the cited documents be considered by the Examiner in the above-identified patent application and that the cited documents be made officially of record therein. It is further requested that a listing of the same appear on the face of any patent which may issue from this application.

This Information Disclosure Statement is being filed within three (3) months of the filing date of the application. Therefore, it is believed that no fees are due under 37 C.F.R. Section 1.97(b)(3).

Respectfully submitted,
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Date: June 8, 2005



FORM PTO-1449	ATTY. DOCKET 033792R003	SERIAL NO. 10/532,674
INFORMATION DISCLOSURE STATEMENT		
APPLICANT: Lei LU, et al.		
FILING DATE April 26, 2005	GROUP ART UNIT 1793	

U.S. PATENT DOCUMENTS

Examiner's Initials	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB-CLASS	FILING DATE, IF APPROPRIATE
	AA					
	AB					
	AC					

FOREIGN PATENT DOCUMENTS

Examiner's Initials	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION YES NO
/S.I./	AD CN 1389597A	1/8/03	China			ABS
/S.I./	AE CN 1181224C	12/22/04	China			
/S.I./	AF CN 1337475A	2/27/02	China			
/S.I./	AG CN 1105398A	7/19/95	China			
	AH					
	AI					
	AJ					
	AK					
	AL					

OTHER INFORMATION (Including Author, Title, Date, Pertinent Pages, Etc.)

/S.I./	AM	P.G. Sanders, et al., "Elastic and Tensile Behavior of Nanocrystalline Copper and Palladium", <i>Acta Mater.</i> Vol. 45, No. 10, pp. 4019-4025 (1997)
/S.I./	AN	R. Suryanarayanan, et al., "mechanical Properties of Nanocrystalline Copper Produced by Solution-Phase Synthesis", <i>Journal of Materials Research</i> , Vol. 11, No. 2, Feb. 1996, pp. 439-448
/S.I./	AO	M. Legros, et al., "Microsample Tensile Testing of Nanocrystalline Metals", <i>Philosophical Magazine A</i> , 2000, Vol. 80, No. 4, pp. 1017-1026
/S.I./	AP	Y.M. Wang, et al., "Microsample Tensile Testing of Nanocrystalline Copper", <i>Scripta Mater</i> , 48 (2003) pp. 1581-1586
/S.I./	AQ	R.K. Islamgaliev et al., "The Determination of the Grain Boundary Width of Ultrafine Grained Copper and Nickel from Electrical Resistivity Measurements", <i>Phys. Stat. Sol. (a)</i> , 162, pp. 559-566 (1997)
/S.I./	AR	Notification Concerning Submission or Transmittal of Priority Document (Form PCT/IB/304) issued in connection with PCT/CN03/00867
EXAMINER: /Skyin Ip/		DATE CONSIDERED: 06/18/2009
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.		